



Edition 2.0 2020-07

INTERNATIONAL STANDARD

Semiconductor devices – STANDARD PREVIEW Part 5-5: Optoelectronic devices – Photocouplers (standards.iten.ai)





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Edition 2.0 2020-07

INTERNATIONAL STANDARD

Semiconductor devices -STANDARD PREVIEW Part 5-5: Optoelectronic devices - Photocouplers i)

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES -

Part 5-5: Optoelectronic devices – Photocouplers

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International Standard IEC 60747-5-5 has been prepared by subcommittee 47E: Discrete semiconductor devices, of IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2007 and Amendment 1:2013. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) optional data sheet basic insulation rating in accordance with IEC 60664-1:2007, 6.1.3.5;
- b) editorial corrections on the use of V_{IORM} ;
- c) editorial corrections on Figure 2: Time intervals for method b);
- d) addition of an alternative surge pulse V_{IOSM} test method.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47E/706/FDIS	47E/714/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60747 series, published under the general title *Semiconductor devices*, can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "http://webstore.iec.ch" in the data related to the specific document. At this date, the document will be

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- withdrawn,
- replaced by a revised edition, or ANDARD PREVIEW
- amended.

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SEMICONDUCTOR DEVICES –

Part 5-5: Optoelectronic devices – Photocouplers

1 Scope

This part of IEC 60747 specifies the terminology, essential ratings, characteristics, safety tests, as well as the measuring methods for photocouplers.

NOTE The term "optocoupler" can also be used instead of "photocoupler".

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1:2013, Environmental testing – Part 1: General and guidance

IEC 60068-2-1, Environmental testing – Part 2-1: Tests – Test A: Cold (standards.iteh.ai)

IEC 60068-2-2, Environmental testing – Part 2-2: Tests – Test B: Dry heat

IEC 60747-5-5:2020

IEC 60068-2-6, Environmental testingatal Parti 2:61s/Tests 1-32Test Fig: 4Vibration (sinusoidal) 76d142074689/iec-60747-5-5-2020

IEC 60068-2-14, Environmental testing – Part 2-14: Tests – Test N: Change of temperature

IEC 60068-2-17, Basic environmental testing procedures – Part 2-17: Tests – Test Q: Sealing

IEC 60068-2-20, Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads

IEC 60068-2-27, Environmental testing – Part 2-27: Tests – Test Ea and guidance: Shock

IEC 60068-2-30, Environmental testing – Part 2-30: Tests – Test Db: Damp heat, cyclic (12 h + 12 h cycle)

IEC 60068-2-58, Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

IEC 60068-2-78, Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state

IEC 60112, Method for the determination of the proof and the comparative tracking indices of solid insulating materials

IEC 60216-1, *Electrical insulating materials* – *Thermal endurance properties* – *Part 1: Ageing procedures and evaluation of test results*

IEC 60216-2, Electrical insulating materials – Thermal endurance properties – Part 2: Determination of thermal endurance properties of electrical insulating materials – Choice of test criteria

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IEC 60664-1:2007, Insulation coordination for equipment within low-voltage systems – Part 1: Principles, requirements and tests

IEC 60672-2, Ceramic and glass insulating materials – Part 2: Methods of test

IEC 60695-11-5, Fire hazard testing – Part 11-5: Test flames – Needle-flame test method – Apparatus, confirmatory test arrangement and guidance

IEC 61000-4-5, Electromagnetic compatibility (EMC) – Part 4-5: Testing and measurement techniques – Surge immunity test

IEC 62368-1:2018, Audio/video, information and communication technology equipment -Part 1: Safety requirements

3 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses: ISO and IEC maintain terminological databases for use in standardization at the following addresses: II ell SIANDARD FKEVIE

- IEC Electropedia: available at http://www.electropedia.org/
- ISO Online browsing platform: available at http://www.iso.org/obp •

https://standards.iteh.ai/catalog/standards/sist/8013222a-1fd1-4e72-b027-3.1 76d142074689/jec-60747-5-5-2020

photocoupler

optoelectronic device designed for the transfer of electrical signals by utilizing optical radiation to provide coupling with electrical isolation between the input and the output

Note 1 to entry: Different types of photocouplers include ambient-rated or case-rated photocouplers, for signal-isolation applications.

3.1.1

DC input photocoupler

photocoupler consisting at the input of a photoemitter to which DC current is applied

3.1.2

AC input photocoupler

photocoupler consisting at the input of antiparallel photoemitters to which AC current is applied

3.1.3

phototransistor output photocoupler

photocoupler whose photosensitive element is a phototransistor

Note 1 to entry: Phototransistor is a transistor in which the current produced by the photoelectric effect in the neighbourhood of the emitter-base junction acts as base current, which is amplified.

3.1.4

photothyristor photocoupler

photocoupler whose photosensitive element is a photothyristor

Note 1 to entry: Photothyristor is a thyristor that is designed to be triggered by optical radiation.

Note 2 to entry: Gate terminal may or may not be provided.

3.1.5

phototriac output photocoupler

photocoupler whose photosensitive element is a phototriac and photocoupler whose photosensitive element is a phototriac and output is triac

-9-

Note 1 to entry: A phototriac is a triac that is designed to be triggered by optical radiation.

3.1.6

IC photocoupler

photocoupler whose photosensitive element is a photodiode/phototransistor and an integrated circuit

3.1.7

FET photocoupler

photocoupler with one or more field-effect transistors (FETs) in the output stage

Note 1 to entry: A FET is activated by photoemitter by direct optical radiation from a photoemitter.

3.1.8

photodiode photocoupler

photocoupler whose photosensitive element is a photodiode or photodiode array

3.1.9

IC input photocoupler

solid state opto-relay

photocoupler whose input element consists of an integrated circuit and a photoemitter

3.1.10

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photocoupler whose output switches digitally without requiring a supply voltage

Note 1 to entry: The term solid state opto-relay standards sist/80132222 - fill_4672-b027photocoupler, phototriac photocoupler and FET/IGBT photocoupler6d142074689/iec-60747-5-5-2020

3.1.11

current transfer ratio

 $H_{\rm f(ctr)}$

ratio of the DC output current to the DC input current, the output voltage being held constant

Note 1 to entry: The abbreviated term CTR (DC) is sometimes used instead of a symbol.

3.1.12

small-signal short-circuit forward current transfer ratio

h_{f(ctr)}

ratio of the AC output current to the AC input current, the output being short-circuited to AC

Note 1 to entry: The abbreviated term CTR (AC) is sometimes used instead of a symbol.

3.2

cut-off frequency

 f_{co}

frequency at which the modulus of the small-signal current transfer ratio has decreased to $1/\sqrt{2}$ of its low-frequency value

3.3

input-to-output capacitance

 C_{IO}

total capacitance between all input terminals or pins connected together and all output terminals or pins connected together

34

isolation resistance

 R_{10}

resistance between all input terminals or pins connected together and all output terminals or pins connected together

3.4.1

repetitive peak off-state voltage for phototriac output and/or solid state opto-relay with triac output

V_{DRM}

maximum applicable repetitive peak reverse voltage between anode and cathode in off-state under specified gate conditions

3.4.2

peak off-state current

I_{DRM}

forward leakage current between the off-state output terminals under specified conditions

3.4.3

peak on-state voltage

 $V_{\rm TM}$

peak forward voltage between on-state output terminals under specified conditions

3.4.4

DC off-state current iTeh STANDARD PREVIEW

IBD

forward leakage current between off-state output terminals under specified conditions

3.4.5

IEC 60747-5-5:2020

DC on-state voltage vs://standards.iteh.ai/catalog/standards/sist/8013222a-1fd1-4e72-b027-76d142074689/iec-60747-5-5-2020

 V_{T}

DC forward voltage between on-state output terminals under specified conditions, when the specified forward current is applied between on-state output terminals

3.4.6 holding current

 $I_{\rm H}$

minimum on-state current in output to maintain the on-state under specified conditions

3.4.7

critical rate of rise of off-state voltage

dV/dt

rate of rise of off-state voltage just before the transition from off-state to on-state under the specified operating conditions

3.4.8

trigger input current

IFT

minimum input forward current to switch from off-state to on-state in output under specified conditions

3.5

common mode transient immunity

CMTI

maximum tolerable rate of rise (or fall) of a common mode voltage (V_{CM}), the specification of which should include the amplitude of the common mode pulse (V_{CM}) , which is applied across the two grounds of the photocoupler and should not exceed the maximum rated transient isolation voltage specification of the photocoupler as defined by the $V_{\rm LOTM}$

3.6

photocoupler providing protection against electric shock

photocoupler which has been subjected to operating conditions (safety ratings) that exceed the specified ratings (limiting values) for normal operation

3.6.1

safety rating

<of a photocoupler> electrical, thermal, and mechanical operating conditions that exceed the specified ratings for reinforced isolation (limiting values) for normal operation, and to which the specified safety requirements refer

3.6.2

electrical safety requirement

<of a photocoupler> electrical requirements for reinforced or double insulation that have to be met and maintained after the photocoupler has been subjected to specified safety ratings, to ensure protection against electrical shock

Note 1 to entry: The photocoupler may become permanently inoperative when safety ratings are applied.

Note 2 to entry: For the definition of double and reinforced insulation, see 3.17.4 and 3.17.5 of IEC 60664-1:2007.

3.6.3

partial discharge

 p_{d}

localized electrical discharge which occurs in the insulation between input and output terminals of the photocoupler

Note 1 to entry: For the technical details of partial discharge, see 3.1 of IEC 60270:2000.

3.6.4

<u>IEC 60747-5-5:2020</u>

apparent charge https://standards.iteh.ai/catalog/standards/sist/8013222a-1fd1-4e72-b027-

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electrical charge caused by a partial discharge in the photocoupler

3.6.5 threshold apparent charge

qтн

specified value of apparent charge that is as small as technically feasible and to which measured values of the partial-discharge inception voltage or extinction voltage, respectively, refer

Note 1 to entry: A threshold apparent charge of 5 pC was found to be a practicable criterion for a photocoupler. Otherwise it should be defined on each individual device design. Smaller values are desirable but are not viable at this time.

Note 2 to entry: In actual tests, this criterion applies to the apparent charge pulse with the maximum value.

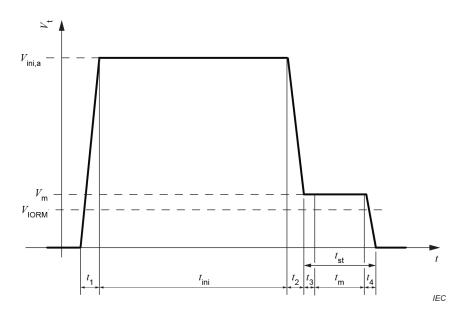
Note 3 to entry: The term "specified discharge magnitude" (see 3.18.2 of IEC 60664-1:2007) is synonymous with "threshold apparent charge".

3.6.6 partial discharge test voltage

 V_{m}

isolation voltage applied during the partial discharge test period

Note 1 to entry: Figure 1 and Figure 2 illustrate the related terms and letter symbols for methods a and b respectively.



- 12 -

- t_{ini} initial time (method a) only)
- t_{st} (partial-discharge) stress time
- t_m (partial-discharge) measuring time
- t_1, t_2, t_3, t_4 settling times

iTeh STANDARD PREVIEW Figure 1 – Time intervals for method a) (standards.iteh.ai)

